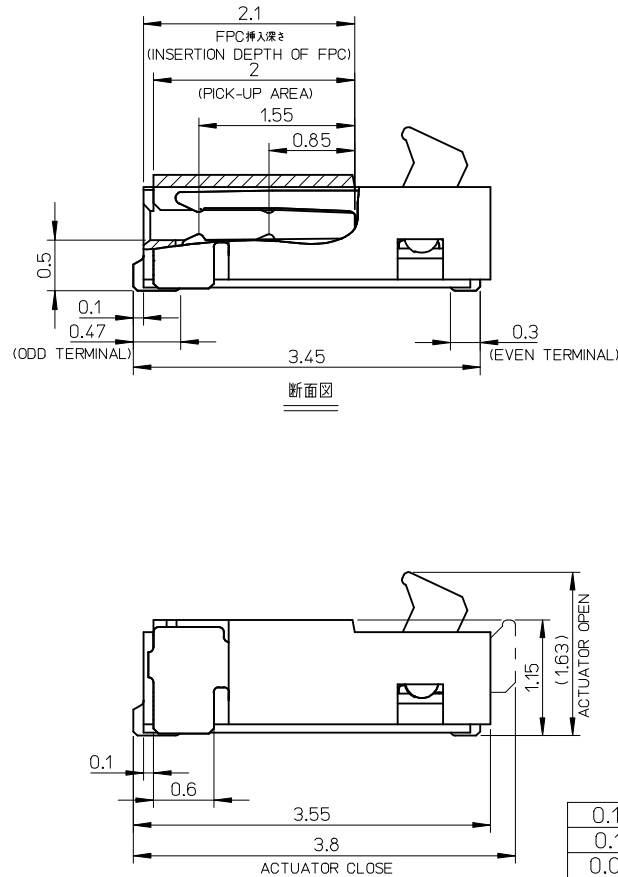
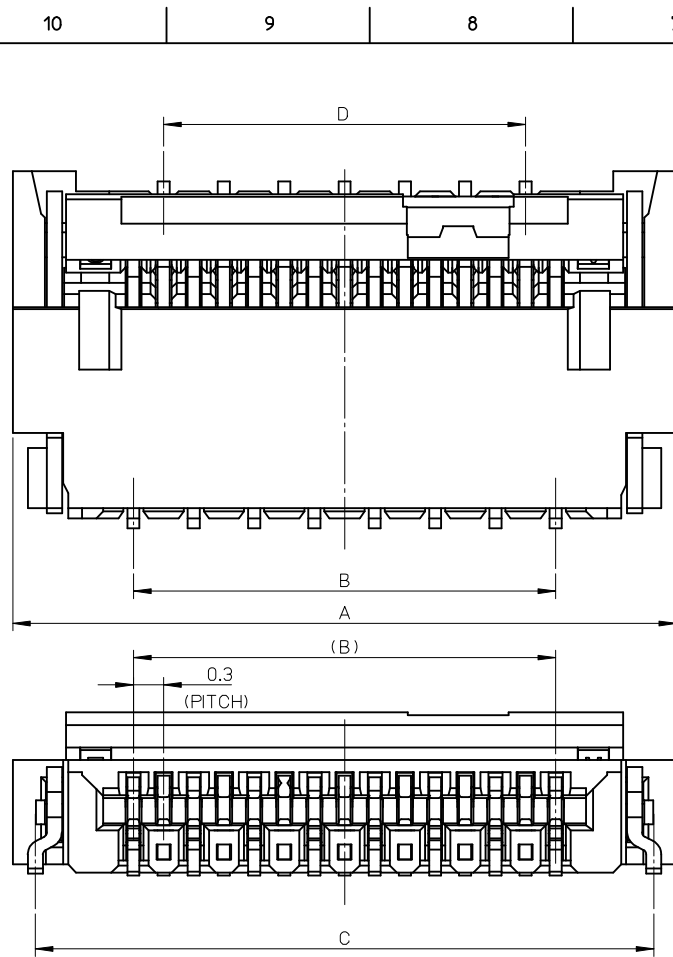




注記 NOTES:

1.材質 MATERIAL

ハウジング: LCP(液晶ポリマー)、白色、ガラス充填、UL94V-0
HOUSING: LIQUID CRYSTAL POLYMER, WHITE (NATURAL)
GLASS FILLED, UL94V-0
アクチュエータ: ポリアミド樹脂

黒色、ガラス充填、UL94V-HB

ACTUATOR: POLYAMIDE

BLACK GLASS FILLED, UL94V-HB

ターミナル: 銅合金 (t=0.12)
TERMINAL: COPPER ALLOY (t=0.12)

金具: 燐青銅 (t=0.15)

NAIL: PHOSPHOR BRONZE (t=0.15)

2.めっき仕様 PLATING

ターミナル TERMINAL

接点部: 金めっき 0.1μm以上

CONTACT AREA: GOLD 0.1 MICROMETER MINIMUM

半田付け部: 金めっき

SOLDER TAIL AREA: GOLD

下地めっき: ニッケル 1.0μm以上

UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM

金具 NAIL

錫めっき 1.0μm以上

TIN PLATING 1.0 MICROMETER MINIMUM

下地めっき: ニッケル 1.0μm以上

UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM

3.平坦度は、0.1ミリ以下とする。

TAILS COPLANARITY TO BE 0.1 MAXIMUM.

4.製品の取り扱いについては、コネクタ取り扱い説明書 (AS-502598-001) を参照願います。

PLEASE REFER TO INSTRUCTION MANUAL (AS-502598-001)
FOR 0.3 FPC CONNECTOR BACK FLIP.

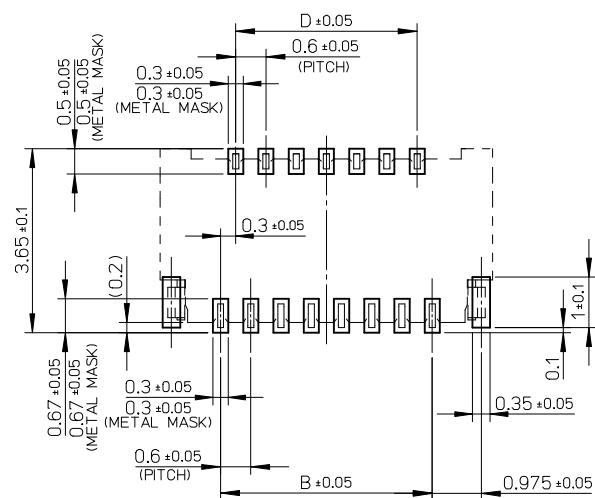
5.ELV及びRoHS適合品

ELV AND RoHS COMPLIANT

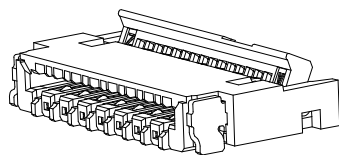
0.125	14.4	16.95	15	17.4	502598-5191	51
0.112	12.6	15.15	13.2	15.6	502598-4591	45
0.085	9	11.55	9.6	12	502598-3391	33
0.077	7.8	10.35	8.4	10.8	502598-2991	29
0.072	7.2	9.75	7.8	10.2	502598-2791	27
0.063	6	8.55	6.6	9	502598-2391	23
重さ (g) WEIGHT (g)	D	C	B	A	EMBOSSED PACKAGE オーダー番号 ORDER NO.	極数 CIRCUITS

CONNECTOR SERIES NO. 502598-xx11

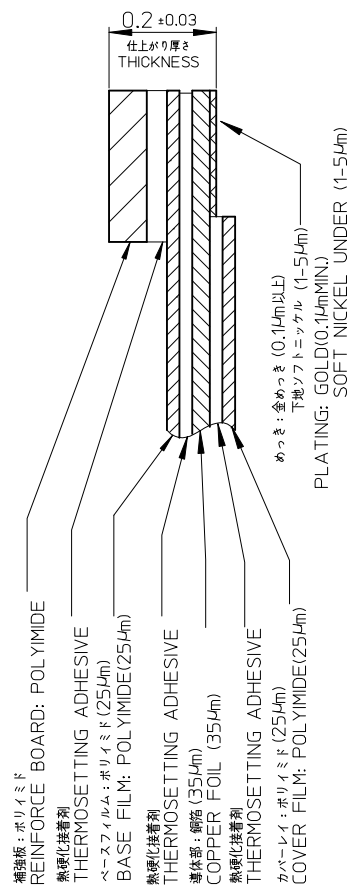
REVISED EC NO: J2014-1481 DRAWN: AYOSHI I01 2014/04/03 CHKD: YKOBAYASHI 02/2014/04/03 APPR: YNOGAWA 2014/04/17	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 20:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY HONO	DATE 2009/07/21	TITLE 0.3 FPC CONN. BACK FLIP HOUSING ASSY				
		10 OVER 30 UNDER	± 0.25	CHECKED BY HSHIMOYAMA	DATE 2009/07/21					
		30 OVER	± 0.3	APPROVED BY KMORIKAWA	DATE 2009/07/21					
		ANGULAR ±1 °		MATERIAL NO.		DOCUMENT NO.				SHEET NO.
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-502598-001				1 OF 2	
	REV	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								



推奨基板寸法
RECOMMENDED P.W.B. PATTERN LAYOUT
推奨メタルマスク厚: t=0.1mm
RECOMMENDED METAL MASK THICKNESS: t=0.1mm

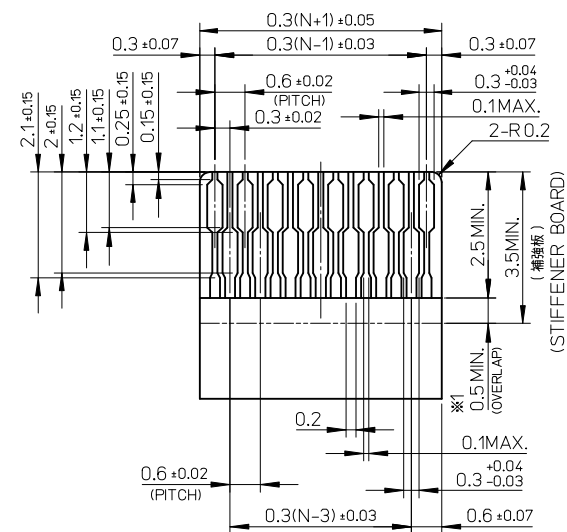


ISO VIEW (参考)



FPC構成推奨仕様

STRUCTURE OF FPC



適合する金めっきFPC推奨寸法
APPLICABLE FPC OF GOLD PATING
RECOMMENDED DIMENSION

(仕上がり厚さ: 0.2 ± 0.03)
(THICKNESS: 0.2 ± 0.03)

FPCについて:

抜き方向は、導体側から補強板側を推奨致します。
 補強フィルム材質は、ポリイミドを推奨致します。
 接着剤は熱硬化接着剤を推奨致します。
 尚、接着剤の接点部への付着は導通不良の原因になりますので、
 染み出しが無い様、お願い致します。

ABOUT FPC:

RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFNER FILM SIDE.
RECOMMENDED MATERIAL:
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE
ADHERING BECAUSE THERE IS A POSSIBILITY THAT
THE EXTRA ADHESIVE CAUSES THE DEFECT IN
ELECTRICAL CONTINUITY.

※1 補強板の長さが図面通りに確保できない場合は、カバーレイと補強板のオーバーラップ寸法を0.5mm以上としてください。
WHEN STIFFENER BOARD DIMENSION CAN NOT SECURE AS DRAWING, PLEASE GIVE THE OVERLAP SIZE OF COVER FILM AND STIFFENER BOARD AS 0.5mm MINIMUM.

REVISED	EC NO: J2014-1481		DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION
	DRAWN: AYOSHI I01 2014/04/03			10 UNDER ± 0.2		DRAWN BY DATE HONO 2009/07/21		TITLE 0.3 FPC CONN. BACK FLIP HOUSING ASSY		
	CHKD: YKOBAYASHI 1022014/04/03			10 OVER 30 UNDER ± 0.25		CHECKED BY DATE HSHI MOYAMA 2009/07/21				
	APPR: YNOGAWA 2014/04/17			30 OVER ± 0.3		APPROVED BY DATE KMORI KAWA 2009/07/21				
				ANGULAR ±1 °		MATERIAL NO.				
D	REV			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-502598-001		2 OF 2
						SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

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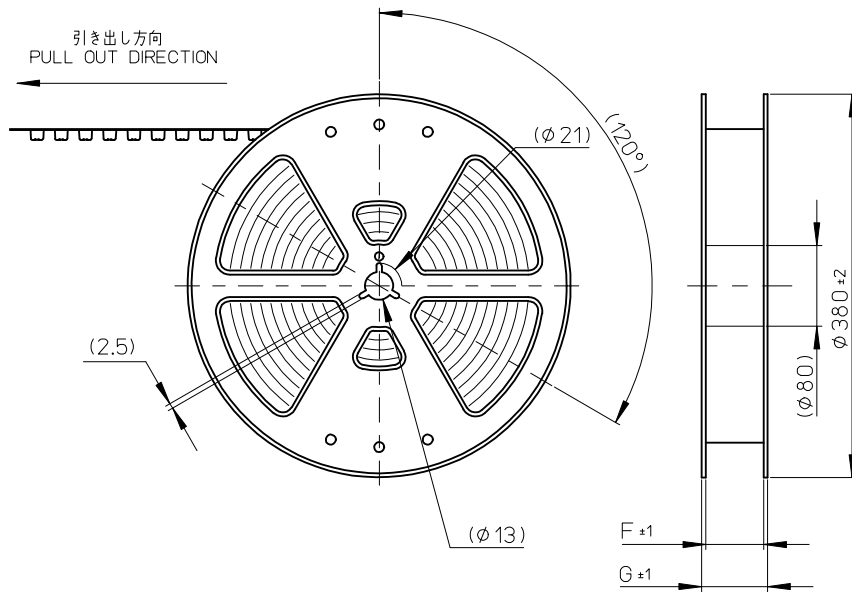
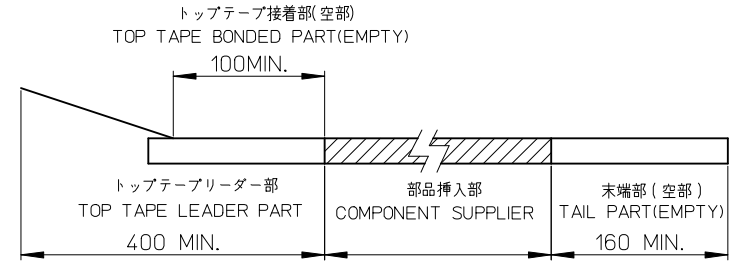
2

1

注記)

NOTES

- 製品番号502598-**11の詳細寸法は、製品単体図面を参照下さい。
IN THE PACKAGE PART NUMBER 502598-**11 DETAIL DIMENSIONS,
SEE SALES DRAWING FOR CONNECTOR.
- 梱包数量: 3000個/リール
NUMBER OF CONNECTORS : 3000 PCS/REEL
- リードテープ長さ
LEAD TAPE LENGTH

引き出し方向
PULL OUT DIRECTION

- カバートープの剥離強度については、IEC60286-3に準拠
COVER TAPE PEEL FORCE IS DEFINED BY IEC 60286-3.

5.材料

MATERIAL

キャリアテープ: ポリスチレン (PS)
CARRIER TAPE: POLYSTYRENE (PS)
トップテープ: ポリエチレンテレフタレート (PET)、他
TOP TAPE: POLYETHYLENE TEREPHTHALATE (PET), OTHERS
リール: ポリスチレン (PS)
REEL: POLYSTYRENE (PS)
6. ELV 及び RoHS 適合品
ELV AND RoHS COMPLIANT

REVISED EC NO: J2014-1481 DRWN:AYOSHI I 01 2014/04/03 CHKD:YKOBAYASHI 02 2014/04/03 APPR:YNOGAWA 2014/04/17	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± ---	DRAWN BY HONO	DATE 2009/07/21	TITLE 0.3 FPC CONN. BACK FLIP TAPING PACKAGE (502598-**11 SERIES)				
		10 OVER 30 UNDER	± ---	CHECKED BY HSHIMOYAMA	DATE 2009/07/21					
		30 OVER	± ---	APPROVED BY KMORIKAWA	DATE 2009/07/21					
		ANGULAR ±1 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-502598-002		1 OF 2			
	REV			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

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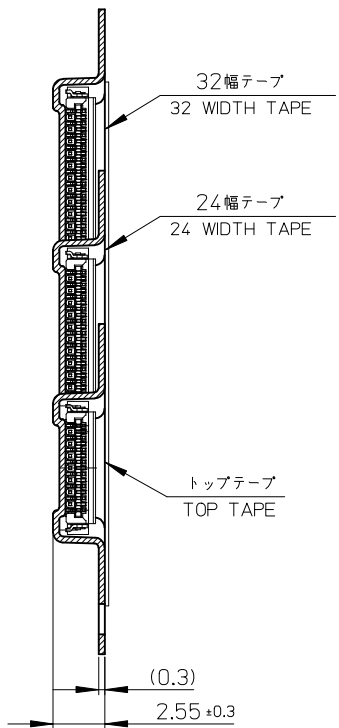
D

C

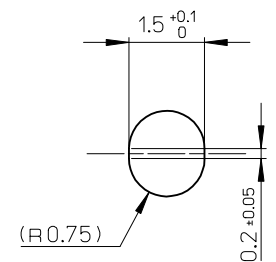
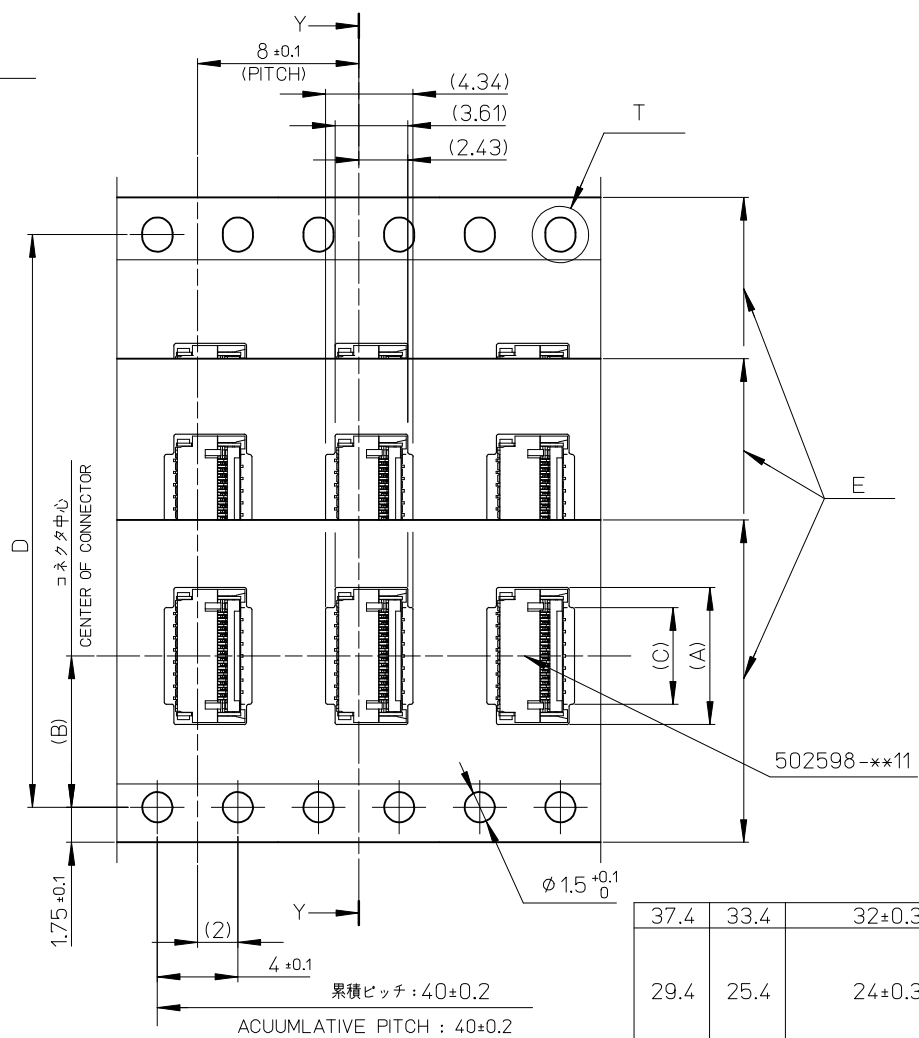
B

A

引き出し方向
PULL OUT DIRECTION



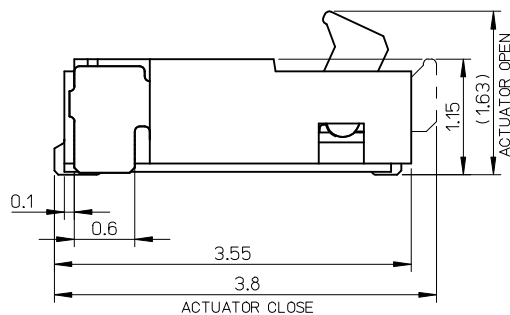
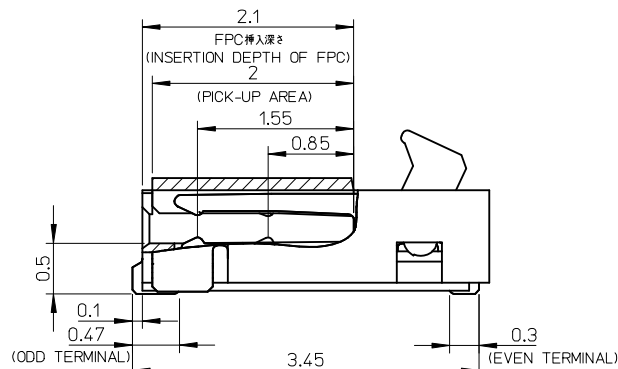
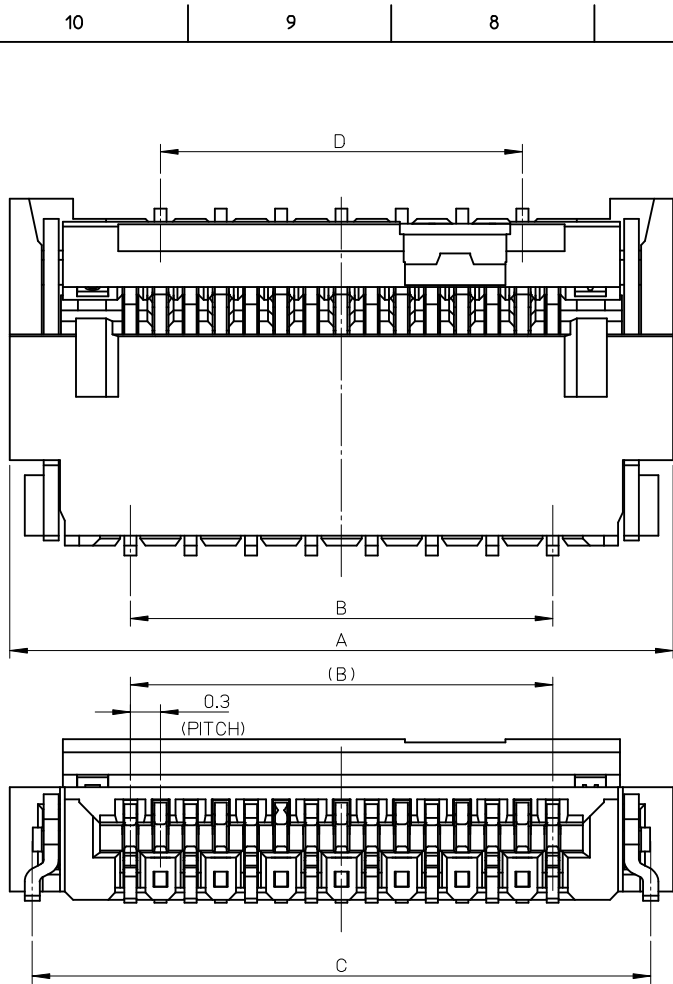
断面 Y-Y
SECTION Y-Y



T 部詳細
DETAIL T

37.4	33.4	32±0.3	28.4	15.7	14.2	17.6	502598-5191	51
29.4	25.4	24±0.3	++	13.9	11.5	15.8	502598-4591	45
				10.3		12.2	502598-3391	33
				9.1		11	502598-2991	29
				8.5		10.4	502598-2791	27
				7.3		9.2	502598-2391	23
G	F	E キャリアテープ幅 EMBOSSED TAPE WIDTH	D	C	B	A	製品番号 MATERIAL NO.	極数 CIRCUITS

REVISED EC NO: J2014-1481 DRWN:AYOSHI I 01 2014/04/03 CHKD:YKOBAYASHI 022014/04/03 APPR:YNOGAWA 2014/04/17	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± ---	DRAWN BY HONO	DATE 2009/07/21	TITLE 0.3 FPC CONN. BACK FLIP TAPING PACKAGE (502598-**11 SERIES) molex				
		10 OVER 30 UNDER	± ---	CHECKED BY HSHIMOYAMA	DATE 2009/07/21					
		30 OVER	± ---	APPROVED BY KMORIKAWA	DATE 2009/07/21					
		ANGULAR ±1 °		MATERIAL NO.						
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-502598-002		2 OF 2		
	REV			SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



注記 NOTES:

1.材質 MATERIAL

ハウジング: LCP(液晶ポリマー)、白色、ガラス充填、UL94V-0
HOUSING: LIQUID CRYSTAL POLYMER, WHITE (NATURAL)
GLASS FILLED, UL94V-0
アクチュエータ: ポリアミド樹脂
黒色、ガラス充填、UL94HB

ACTUATOR: POLYAMIDE
BLACK GLASS FILLED, UL94HB

ターミナル: 焼青銅 (t=0.12)
TERMINAL: PHOSPHOR BRONZE (t=0.12)

金具: 焼青銅 (t=0.15)
NAIL: PHOSPHOR BRONZE (t=0.15)

2.めっき仕様 PLATING

ターミナル TERMINAL

接点部: 金めっき 0.1μm以上
CONTACT AREA: GOLD 0.1 MICROMETER MINIMUM

半田付け部: 金めっき
SOLDER TAIL AREA: GOLD

下地めっき: ニッケル 1.0μm以上
UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM

金具 NAIL

錫めっき 1.0μm以上
TIN PLATING 1.0 MICROMETER MINIMUM

下地めっき: ニッケル 1.0μm以上
UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM

3.平坦度は、0.1ミリ以下とする。

TAILS COPLANARITY TO BE 0.1 MAXIMUM.

4.ELV及びRoHS適合品

ELV AND RoHS COMPLIANT

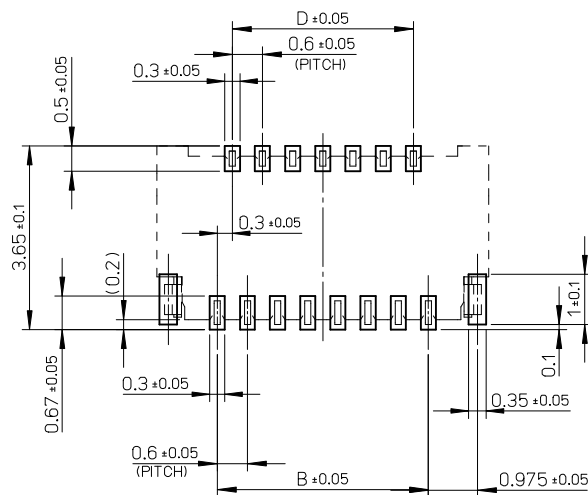
5.本製品は502598-**-91の端子材料変更品である。

THIS PRODUCT IS CHANGE OF TERMINAL MATERIAL
FOR 502598-**-91.

0.125	14.4	16.95	15	17.4	502598-5193	51
0.112	12.6	15.15	13.2	15.6	502598-4593	45
0.105	11.4	13.95	12.0	14.4	502598-4193	41
0.098	10.8	13.35	11.4	13.8	502598-3993	39
0.085	9	11.55	9.6	12	502598-3393	33
0.077	7.8	10.35	8.4	10.8	502598-2993	29
0.072	7.2	9.75	7.8	10.2	502598-2793	27
0.068	6.6	9.15	7.2	9.6	502598-2593	25
0.063	6	8.55	6.6	9	502598-2393	23
0.048	4.2	6.75	4.8	7.2	502598-1793	17
0.043	3.6	6.15	4.2	6.6	502598-1593	15
重さ (g) WEIGHT(g)	D	C	B	A	EMBOSSED PACKAGE オーダー番号 ORDER NO.	極数 CIRCUITS

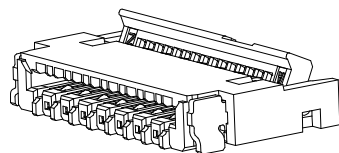
CONNECTOR SERIES NO. 502598-**-21

REVISED EC NO: J2014-0146 DRW: KINAGUMO CHKD: TAKAHASHI APPR: YNOGAWA 2013/07/25 2013/08/30 2013/08/28	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	KMIYAHARA	2012/07/18	TITLE 0.3 FPC CONN. BACK FLIP HOUSING ASSY molex				
		10 OVER 30 UNDER	± 0.25	KTAKAHASHI	2012/07/18					
		30 OVER	± 0.3	KMORIKAWA	2012/08/01					
		ANGULAR ±1 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-502598-003		1 OF 2			
REV	B			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

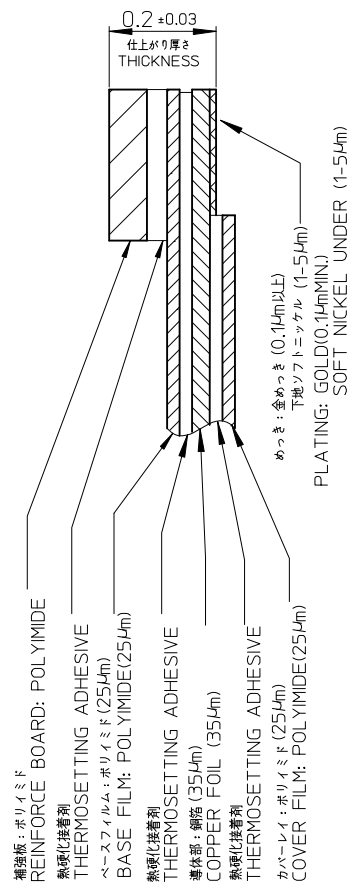


RECOMMENDED P.W.B. PATTERN LAYOUT

マスク厚: 100 μ m
マスク開口率: 100%
SCREEN THICKNESS: 100 μ m
SCREEN OPEN RATIO: 100%

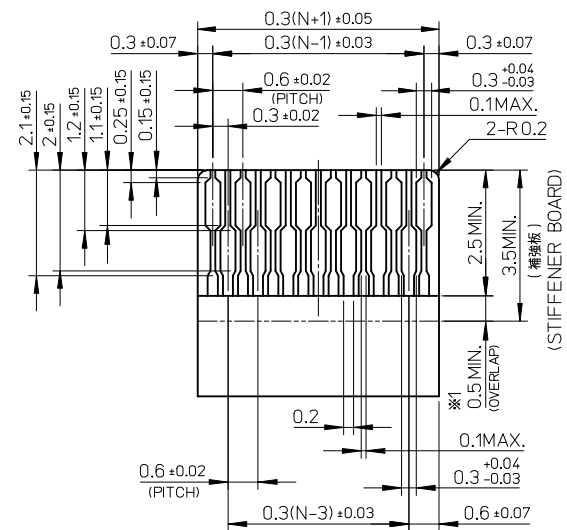


ISO VIEW (参考)



FPC構成推奨仕様

STRUCTURE OF FPC



適合する金めっきFPC推奨寸法
APPLICABLE FPC OF GOLD PATING
RECOMMENDED DIMENSION

(仕上がり厚さ : 0.2 ± 0.03)
(THICKNESS: 0.2 ± 0.03)

FPCについて:

抜き方向は、導体側から補強板側を推奨致します。

補強フィルム材質は、ポリイミドを推奨致します。

接着剤は熱硬化接着剤を推奨致します。

尚、接着剤の接点部への付着は導通不良の原因になりますので、

染み出しが無い様、お願い致します。

ABOUT FPC:

RECOMMENDED PUNCHER DIRECTION:

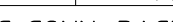
FROM CONDUCTOR SIDE TO STIFFNER FILM SIDE.

RECOMMENDED MATERIAL:

STIFFENER FILM : POLYIMIDE

BONDING AGENT : THERMOSETTING AGENT

PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

REVISED EC NO: J2014-0146 DRAWN: KAGUMO CHK'D: K TAKAHASHI APP'R: YNOGAWA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
		10 UNDER	± 0.2	DRAWN BY KMIYAHARA	DATE 2012/07/18	TITLE 0.3 FPC CONN. BACK FLIP HOUSING ASSY			
		10 OVER 30 UNDER	± 0.25	CHECKED BY KTAKAHASHI	DATE 2012/07/18				
		30 OVER	± 0.3	APPROVED BY KMORIKAWA	DATE 2012/08/01				
		ANGULAR ±1 °		MATERIAL NO.					
	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE TABLE		SD-502598-003		2 OF 2		
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									